

Descriptions

TIM-GAP Soft is designed to meet industry's rapidly growing need for interface material with high thermal conductivity and maximum conformability for extremely low stress applications. **TIM-GAP Soft** is a clean, production friendly and of the low modulus type of interface material. The viscoelastic nature of this material provides the highest level of protection against damage due to deformation as well as shock or vibration.

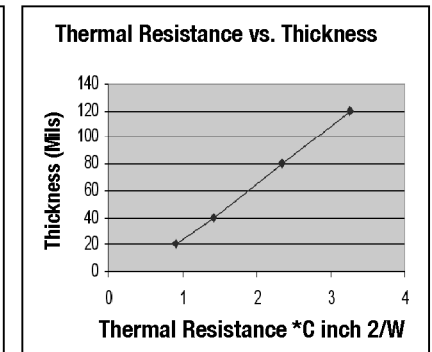
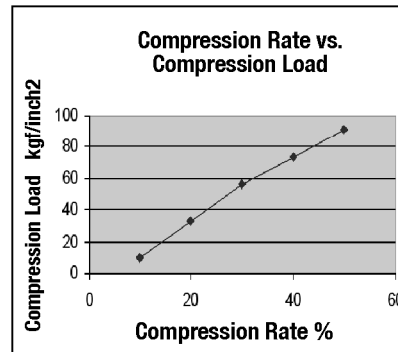
Key Features

- High Thermal Conductivity
- Electrically Insulating
- Smooth and highly compliant surface
- Eliminates the mess of grease
- Clean and easy to apply
- Will not dry out, high temperature resistance
- No out gassing under vacuum
- Re-workable/Clean release from device

Applications

- Interface for discrete semiconductors requiring low pressure or spring clamp mounting
- CDROM Cooling
- Medical devices
- Between CPU and Heat Spreader
- Consumer electronics
- Industrial controls

PHYSICAL PROPERTY	TEST METHOD	TIM-GAP SOFT
Type		Silicone
Color	Visual	Gray
Operating Temp. range °C		-60 to 200
Tensile Strength. MPa	ASTM D-412	0.3
Hardness. Shore 00	ASTM D-2240	48
Thermal Conductivity. W/m ² k	ASTM D-5470 Modified	1.3
Thermal Resistance. °C-inch ² /W @ 0.020" thickness	ASTM D-5470 Modified	0.90
Breakdown Voltage	ASTM D-149	>6000
Volume Resistivity, Ohm-cm	ASTM D257	10 ¹⁴
Available thickness, inch.		0.020-0.125



Availability

- **TIM-GAP Soft** is available in 300mm x 200mm sheets or die-cut parts. This material can apply with "pick & place" and other types of high volume production dispensing equipment.
- Materials are available standard and/or special shape and size.
- Tooling charges vary depending on tolerances and complexity of the part
- TIM-GAP Soft materials are available with or without fiber glass reinforcement and/or hard surface for ease of handling and installation in standard or complex assemblies.



Disclaimer: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performances. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not be construed as recommendations to infringe any patent